

Title (en)

MODULE FOR WIRELESS COMMUNICATION AND METHOD FOR PRODUCING A MODULE FOR WIRELESS COMMUNICATION

Title (de)

MODUL ZUR DRAHTLOSEN KOMMUNIKATION UND VERFAHREN ZUM HERSTELLEN EINES MODULS ZUR DRAHTLOSEN KOMMUNIKATION

Title (fr)

MODULE DE COMMUNICATION SANS FIL ET PROCÉDÉ DE FABRICATION D'UN MODULE DE COMMUNICATION SANS FIL

Publication

**EP 2926409 A1 20151007 (DE)**

Application

**EP 13788706 A 20131023**

Priority

- DE 102012221940 A 20121130
- EP 2013072150 W 20131023

Abstract (en)

[origin: WO2014082800A1] The invention relates to a module (100) for wireless communication, wherein the module (100) has a module body (102) and a folded dipole (104). The module body (102) is plate-shaped and has a structure having several levels. The module body (102) has a circuit region (106). The folded dipole (104) has a first dipole half (302) and a second dipole half (304) and is arranged peripherally around the circuit region (106). The first dipole half (302) is arranged in a first level of the module body (102) and the second dipole half (304) is arranged in a second level of the module body (102). The first dipole half (302) and the second dipole half (304) are separated by a layer of the module body (102) and are connected to each other in an electrically conductive manner by the layer by means of a first via (110) and a second via (112).

IPC 8 full level

**H01Q 1/38** (2006.01); **H01Q 9/26** (2006.01)

CPC (source: EP US)

**H01Q 1/38** (2013.01 - EP US); **H01Q 9/065** (2013.01 - US); **H01Q 9/26** (2013.01 - EP US)

Citation (search report)

See references of WO 2014082800A1

Citation (examination)

- US 2009058738 A1 20090305 - SAKUMA MASAO [JP], et al
- EP 1363359 A1 20031119 - ALPS ELECTRIC CO LTD [JP]

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**WO 2014082800 A1 20140605**; CN 104798255 A 20150722; CN 104798255 B 20180330; DE 102012221940 A1 20140605; DE 102012221940 B4 20220512; EP 2926409 A1 20151007; JP 2016506121 A 20160225; JP 6290239 B2 20180307; KR 20150091475 A 20150811; TW 201429338 A 20140716; TW I629922 B 20180711; US 2015295319 A1 20151015; US 9698485 B2 20170704

DOCDB simple family (application)

**EP 2013072150 W 20131023**; CN 201380062412 A 20131023; DE 102012221940 A 20121130; EP 13788706 A 20131023; JP 2015544396 A 20131023; KR 20157014280 A 20131023; TW 102143364 A 20131128; US 201314646597 A 20131023